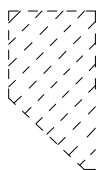
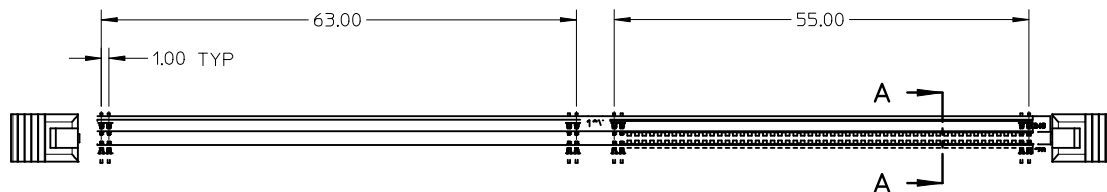
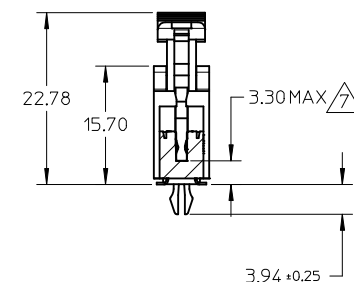


10 9 8 7 6 5 4 3 2 1



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SECTION A-A

NOTES:

1. MATERIALS
HOUSING - HIGH TEMP LCP GLASS FILLED, UL 94V-0, BLACK
EJECTORS - HIGH TEMP NYLON GLASS FILLED, UL 94V-0, BLACK
TERMINALS - COPPER ALLOY
2. PLATING OPTION - PLS REFER TO SHEET 5.
3. CARD SLOT ACCEPTS 1.27±0.10MM MODULE THICKNESS. (MEASURED OVER PC PADS)
4. RECOMMENDED MODULE LAYOUT SHALL BE AS PER JEDEC MO-237. PLS REFER TO SHEET 3.
5. PRODUCT IS PACKED INTO TRAYS. WRAP IN MOISTURE BARRIER BAG WITH SILICA GEL.
6. MOLEX LOGO, DATE CODE & PART NO. INDICATED ON HOUSING.
7. DIMM MODULE SEATING PLANE FROM TOP OF PCB.
8. COPLANARITY FOR SOLDER TAILS SHALL NOT EXCEED 0.20MM.
9. REFER TO PRODUCT SPEC. PS-87966-001 FOR PERFORMANCE SPECIFICATIONS.
10. THE KEEP OUT AREA IS THE AREA WHERE THE CONNECTOR IS MOUNTED ONTO THE PCB, WHICH DOES NOT INCLUDE THE LATCH.
11. KEEP OUT ZONE AS PER JEDEC SO-001.
12. CONTACT MOLEX FOR AVAILABILITY OF PRODUCT OPTIONS.

ADDED MBB & S.GEL EC NO: S2012-0451 2012/12/07 DRWN:CTEH CHKD:KSOH 2013/01/03 APPR:SHLENI 2013/01/03	DESCRIPTION REV	QUALITY SYMBOLS 	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION				
				mm	INCH	DRAWN BY CCTEH	DATE 2005/10/19	TITLE DDR2 DIMM, 1.00MM PITCH 240 CKTS, SMT					
			4 PLACES	± ---	± ---	CHECKED BY SRRAMESH	DATE 2005/11/21						
			3 PLACES	± ---	± ---	APPROVED BY GGLEE		DATE 2005/11/21	molex				
			2 PLACES	± 0.10	± ---								
			1 PLACE	± ---	± ---								
0 PLACE	±	±	MATERIAL NO.		DOCUMENT NO.		SHEET NO.						
DRAFT WHERE APPLICABLE			SEE TABLE		SD-87966-002				1 OF 5				
MUST REMAIN WITHIN DIMENSIONS			SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION									

9 8 7 6 5 4 3 2 1